

APPENDIX

Changes to Claims:

The following are marked-up versions of the amended claims:

7. (Amended) The semiconductor device as defined in claim 1 ~~any one of claims 1 to 6~~,
wherein a recognition hole is formed in the substrate at a position differing from the holes; and
wherein a recognition pattern is formed over the recognition hole on the side of a surface of the substrate including the interconnecting pattern.
10. (Amended) The semiconductor device as defined in claim 1 ~~any one of claims 1 to 6~~,
wherein the conductive members are a plurality of layered bumps.
17. (Amended) The semiconductor device as defined in claim 1 ~~any one of claims 1 to 6~~,
wherein the semiconductor chip is mounted face-down to the substrate.
18. (Amended) A circuit board over which is mounted the semiconductor device as defined in claim 1 ~~any one of claims 1 to 6~~.
19. (Amended) An electronic instrument provided with the semiconductor device as defined in claim 1 ~~any one of claims 1 to 6~~.
27. (Amended) The method of fabricating a semiconductor device as defined in claim 20 ~~any one of claims 20 to 26~~, further comprising
a step of forming a recognition hole in the substrate at a position differing from the holes, and forming a recognition pattern over the recognition hole on the side of a surface of the substrate including the interconnecting pattern.

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